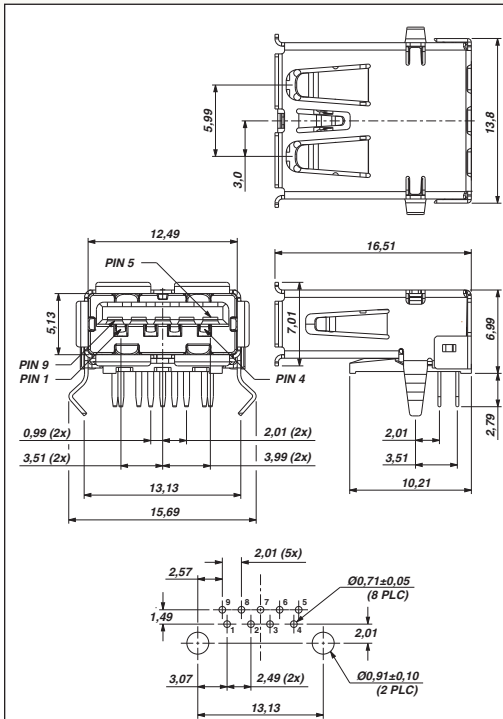
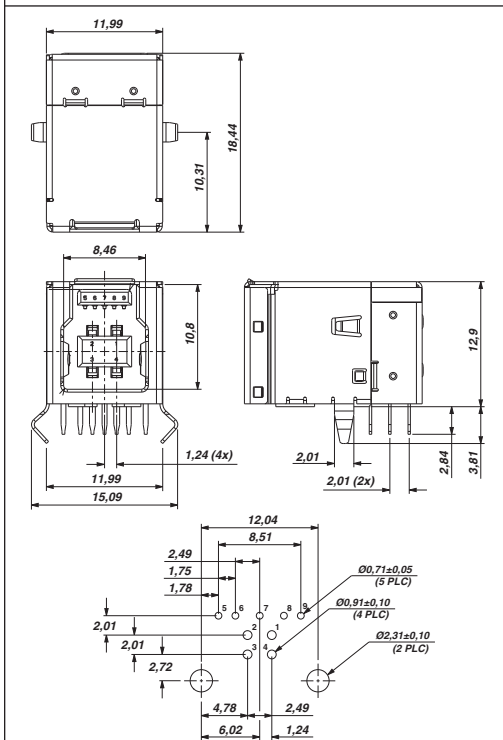


## SERIES 896, 897 • UNIVERSAL SERIAL BUS 3.0 • SOCKETS



**FIG. 1**



**FIG. 2**

- USB 3.0 receptacles for through-hole mount
- Plug retention tabs
- Kinked locating legs for secure PCB retention
- Fully shielded
- Fully backwards compatible with USB 2.0
- 10X faster than USB 2.0 and provides optimized power efficiency
- Packaged in trays:  
896-46-009-90-300000 - 100 pieces per tray  
897-46-009-90-300000 - 80 pieces per tray



## ORDERING INFORMATION

<b>FIG. 1</b>	<b>USB 3.0 Type A Receptacle, Single, Through-Hole</b>
	896-46-009-90-300000
<b>FIG. 2</b>	<b>USB 3.0 Type B Receptacle, Single, Through-Hole</b>
	897-46-009-90-300000

## Technical Specifications

### Materials:

Terminals: Copper Alloy, Tin-Plated  
 Contacts: Copper Alloy, Gold Flash over PdNi  
 Casing and Shield: Stainless Steel  
 Insulator material: High temperature thermoplastic rated UL94V-0



### Ratings:

Voltage: 30VAC (rms)  
 Current: 1.5A PWR/GND pins  
 All housing materials rated for "lead-free" soldering up to 260° C

### Electrical:

Contact resistance: 30mΩ max. for power and ground pins  
 50mΩ max. for all others  
 Insulation resistance: 100MΩ min.  
 Dielectric withstanding voltage: 100VAC at sea level  
 Capacitance: 2pF max.

### Mechanical:

Random vibration: No discontinuity >1μs per EIA 364-28, cond. VII, letter D  
 Physical shock: No discontinuity >1μs per EIA 364-27, condition H  
 Durability: 5000 cycles min. per EIA 364-09  
 Mating force: 35 Newtons max. per EIA 364-13  
 Unmating force: Initial - 10 Newtons min. per EIA 364-13  
 After test - 8 Newtons min. per EIA 364-13

### Environmental:

Thermal shock per EIA 364-32, condition I  
 Humidity per EIA 364-31  
 Temperature life per EIA 364-17, method A  
 Solderability per EIA 364-52, category 2